



Request for quote and specifications of - Manual Ultrasonic Eutectic & Die Bonder

- The GEECI (Gallium Nitride Ecosystem Enabling Centre and Incubator) at SID-Indian Institute of Science is seeking bids from qualified industries for **Manual Ultrasonic Eutectic & Die Bonder**.
- Companies need to submit two bids, a technical bid and a commercial bid, in two separate sealed envelopes. The bids should be submitted no later than 21 days from the date of posting of this tender, as listed on the website date/time stamp and by 5 pm on the 21st day or next weekday in case the 21st day falls on a weekend or a national holiday.
- Both technical and commercial bids should be addressed to “The Chief Executive, SID, IISc, Bangalore 560012.”
- The envelopes should be addressed to “Prof. Srinivasan Raghavan, CeNSE, IISc, Bangalore, 560012” and submitted to the office at CeNSE, IISc in Room No. GF 15 between 9 am and 5 pm.
- All questions regarding this tender should be addressed to Prof. Srinivasan Raghavan at the email address sraghavan@iisc.ac.in
- Post such submission all vendors should send an email to sraghavan@iisc.ac.in with the subject line: “GEECI_Bidder’s name_Tool Name” to intimate him of the submission within one day.
- Deviations from the technical specifications requested are allowed. Such deviations must be highlighted and justified. Their acceptance or rejection will be left to the discretion of the technical committee.
- The equipment sought will be placed at the Centre for Nano Science and Engineering (CeNSE), Indian Institute of Science (IISc). IISc is India’s No. 1 institution on higher learning and the Centre for Nano Science and Engineering is home to one of the best academic fabs in the world.
- The technical response, corresponding to the tool being offered, should be in the form of a compliance table with at least 5 columns. Serial number in column 1. Each of the numbered technical items below should be addressed in a separate row of the table in column 2. Compliance to this requirement, in Yes/No, deviation from it and justification should be provided in the neighbouring columns 3-5. Post the opening of a hard copy of the technical bid the committee will request for a soft copy of the files for further processing. Companies should NOT mail soft copies of the files unless specifically requested for.
- Detailed technical specifications of the tool being offered should be included.
- Any additional capabilities or technical details, that you would like to bring to the attention of the purchase committee, can be listed at the end of the technical table.
- If multiple systems can fulfil the requirements, vendors can submit multiple bids.
- Vendors are encouraged to highlight the advantages of their tools over comparable tools from the competitors.
- The commercial bid should be broken up to the maximum extent possible into separate items with a cost against each to enable better comparison of price for various configurations across the bidders. As an option, please provide itemized cost for any suggested accessories/add-ons that may enhance the usability, capability, accuracy or reliability of the tool. Vendors are encouraged to quote for as many add-ons as their tool portfolio permits.

Technical Specifications Manual Ultrasonic Eutectic & Die Bonder

Sl No	Description & Specifications		Compliance - Yes / No	Remarks
1	Application: This system is required to Die bond (Precise die bonding (face up) on HMC, TO, RF packages & Flat substrate (PCB , ceramic & QFN) etc. Type circuits which includes semiconductor chips & package. Flip chip bonding ((face down)) is also required as an optional item.			
2	Machine Capability	Ultrasonic as well as thermosonic		
3	Die bonder should be capable to bond:	Die bonding (Only die pick & place)		
		Ultrasonic / Motorized Eutectic Die Bonder (Bondable Preform Alloys)		
4	Bondable Preform Alloys in Eutectic	AuSn, AuSi, AuGe, and others		
5	Eutectic Die Size Range	0.1mm to 4.5mm or more		
6	After dispense epoxy Die bondable Size	0.1mm to 10mm		
7	Independent preform and die cycles	ON & OFF		
8	Placement Accuracy	± 1 mil (± 25.4 um)		
9	Bond Head Movement	Motorized vertical movement only		
10	Bond Actuation	By touchdown sensor		
11	Placement Table Motion	Manipulator 6:1 or better		
12	Ultrasonic System	Frequency in range of 60 KHz to 65 KHz		
13	Scrub Amplitude	0-3 um or better		
14	Dwell Time (before scrubbing)	0 to 9.9 seconds.		
15	Bond Force	12 to 300 grams or better		
16	Z Travel/Vertical Bonding	28mm or better		
17	Bond head vertical movement can be controlled in fast or slow speed on manual mode.	Adjustable		
18	Deep access capable (when using long collet)	Accessible		
19	Collet Temperature	Ambient to 250°C		
		Ambient to 500°C		
20	Work Stage	Clamping & Vacuum system.		
21	Supply Voltage @ 50 Hz	180 – 250 VAC (Indian Std)		
22	Stereo Microscope with Camera	Microscope (up to 100x magnification) or better with Digital Video Camera and 15“ Screen or better		



Society for Innovation & Development



23	Illumination	Dual Optical fiber or better		
24	AuSn, AuSi, AuGe	10 X 10 Cms each solder preform		
25	Die Bond(Pickup Tools Size)	0.7 to 5mm Pickup tools need to supply along with machine		
26	Stereo Microscope with Camera	Microscope (up to 100x magnification) or batter with Color CCTV Systems with or without single reticle (target) generator.		
27	Bonding target system	laser or batter		
28	Bonder Installation tool:	The kit should include essential items like tweezers, scissors, Allen wrenches, Screws and Ball end drivers		
29	Operation & Maintenance Manual of machine (hard copy & soft copy both)			
30	Supplier should provide 1 year warranty on-site			
31	Supplier should provide support and service for 10 years after warranty period			
32	Supplier should provide free onsite training			

Common Terms and Conditions: A separate table to be included for each of the items below in the technical bid.			
I	Semi Standards: Technical bid should provide details of SEMI standards the tool confirms to.		
II	Clean Room Compatibility: The system should be compatible with better than class 1000 cleanroom environment.		
III	Tool Qualification and Acceptance: Commissioning shall involve demonstration of Manual Ultrasonic Eutectic & Die Bonder to the required specifications and characterized by the client within time frames as mutually agreed upon. Details of the stage wise certification protocols to be pursued for tool acceptance should be included in the technical bid. The PO will include a mutually agreed upon set of tool qualification criteria. Please list a set of acceptance tests for on-site (vendor) inspection and after installation at IISc.		
IV	Tool Training: The bid should include as an option the cost of training personnel on site before shipment and post installation at IISc.		
V	Tool footprint and utilities: A floor plan should be part of the technical bid. A list of utility requirements should be part of the technical bid. The system should be compatible with 240±10V, 50 Hz single phase or 415±20V, 50 Hz 3 phase supplies. The MINIMUM sets of utility requirements needed are provided in Table 1. If there are additional utility requirements please include them in the technical bid. Please list connector types for all utilities.		
VI	Cost of Ownership and supply of spares: The quote should include a listing of spares that need to be replaced periodically to ensure that the system is in operation in a stable fashion – the stability parameters being defined by the vendor and agreed to by the client – the cost of such items, the ability to guarantee their availability at this cost for a period of 5 years from the time of procurement. The aim of this exercise is to compare cost of ownerships between reactors.		
VII	Maintenance: The cost of an annual maintenance contract and cost of emergency technical support that may involve an engineer being on site should be quoted for in the commercial bid and addressed in the technical bid. The availability of trained engineers in India for servicing the system will be preferred and should be described in the technical bid.		
VIII	Maintenance: On all systems a set of basic tools required -non-standard screw or spanner head that is required for routine tool maintenance should be mentioned- for performing routine maintenance should be included.		
IX	Operation & Maintenance: System operation, process and troubleshooting manuals and detailed drawings are a must (hard copy & soft copy both). Their inclusion must be indicated in the technical bid.		
X	Online support: System should have the capability for online diagnostics from a remote location in case of tool problems or tele-con with free of cost.		



Society for Innovation & Development



XI	Post sales & service and Indian Presence: Bidders should provide details of after sales service and support available in India. If not India, the nearest geographical location should be specified. Please provide details of the number of trained personnel in India who can service the machine, the number of tools sold in India and the corresponding number in the southern region or in Bangalore.		
XII	Shipping: On all systems the cost of shipping up to IISc should be included (DAP MODE).. IISc will help with customs clearance at Bangalore Airport.		
XIII	Payment Terms and Conditions: On all systems the payment terms should be specified in the technical and commercial proposal and is subject to negotiation. Please include your payment option. IISc would prefer to retain at least 20% of payment till instruments have been commissioned and successfully demonstrated.		
XIV	References: Bidders should provide details of other locations in India with similar tool installations.		
XV	References: Bidders should provide details of at least 3 other locations globally where similar tool installations have been deployed for device fabrication in a clean room preferably for production purposes.		
XVI	Company financials: Bidder shall have to submit audited accounts of financial year 2017-18, 2018-19 and 2019-20. Audited statement must be signed and stamped by qualified chartered accounted. Income Tax return for assessment year – 2017-18, 2018-19 and 2019-20.		
XVII	The following documentation should be provided. ISO9001 quality certification. CE marking confirmation.		

Eligibility Criteria :	
1	Only vendors who are compliant with the technical requirements will be considered for commercial comparison. The bid is awarded to the lowest cost vendors (referred as L1).
2	The Bidder's firm should have existence for a minimum of 5 years. (Enclose Company Registration Certificate).
3	Quote should only from Indian Original Equipment Manufacturer (OEM).
4	The quotations should be on For-IISc Bangalore basis in INR only.
5	The Bidder should belong to either class 1 or class 2 supplier distinguished by their "local content" as defined by recent edits to GFR. They should mention clearly which class they belong to in the cover letter. a) Class 1 supplier: Goods and services should have local content of equal to or more than 50%. b) Class 2 supplier: Goods and services should have local content of equal to or more than 20 % and less than 50%.
6	This tender will only apply entertain Class 1 or Class 2 suppliers. Vendors must provide a self-declaration of what Class they belong to.
7	Mention GST separately.
8	GST/other taxes, levies etc., are to be indicated separately. The BIDDER should mention GST Registration and PAN in the tender document.
9	The bidder should sign and submit the declaration for Acceptance of Terms and Conditions
10	The Bidder must not be blacklisted/banned/suspended or have a record of any service-related dispute with any organization in India or elsewhere. A declaration to this effect has to be given.
11	The products should be based on latest technology for the specific requirement.
12	Incomplete bids will be summarily rejected.

Details to be provided in addition to other utility requirements the tool may require. If not applicable mark as NA: Not applicable.

Tool dimensions				Electric	Chilled water		Gases								Exhaust	Thermic load	
L (mm)	B (mm)	H (mm)	Sq. Metre	kW	kVA	kW	l/h	slpm	slpm	slpm	slpm	slpm	slpm	slpm	slpm	m ³ /h	kW
Tool Foot Print, (LXBXH)				Power consumption average	Peak power	Cooling capacity maximum	Process Cooling Water	UHP Nitrogen	UHP Hydrogen	He	Oxygen	Regular Nitrogen	Argon	Forming Gas			Thermic load to clean room
			Area														